<u>TOSHIBA</u>

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSII)

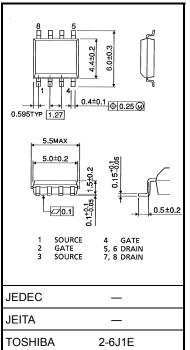
TPC8305

Lithium Ion Battery Applications Portable Equipment Applications Notebook PC Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance $: RDS (ON) = 24 \text{ m}\Omega (typ.)$
- High forward transfer admittance : $|Y_{fs}| = 12 S (typ.)$
- Low leakage current $: I_{DSS} = -10 \ \mu A \ (max) \ (V_{DS} = -20 \ V)$
- Enhancement mode $: V_{th} = -0.5 \sim -1.2 \text{ V} (V_{DS} = -10 \text{ V}, \text{ ID} = -1\text{mA})$

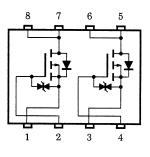
Absolute Maximum Ratings (Ta = 25°C)

Char	acteristics	Symbol	Rating	Unit	
Drain-source vol	tage	V _{DSS}	-20	V	
Drain-gate voltag	ge (R _{GS} = 20 k Ω)	VDGR	-20	V	
Gate-source volt	age	V _{GSS}	±12	V	
Drain curren	DC (Note 1)	ID	-5	A	
Drain curren	Pulse	I _{DP}	Joss -20 /DGR -20 /DGR -20 /GSS ±12 ID -5 IDP -20 PD (1) 1.5 PD (2) 1.0 PD (2) 0.45 EAS 32.5 IAR -5 EAR 0.10 Tch 150		
Drain power dissipation (t = 10s) (Note 2a)	Single-device operation (Note 3a)	P _{D (1)}	1.5	W	
	Single-device value at dual operation (Note 3b)	P _{D(2)}	1.0		
Drain power dissipation	Single-device operation (Note 3a)	P _{D (1)}	0.75	10/	
(t = 10s) (Note 2b)	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.45	W	
Single pulse avalanche energy (Note 4)		E _{AS}	32.5	mJ	
Avalanche currei	nt (Note 1)	I _{AR}	-5	А	
Repetitive avalanche energy Single-device value at operation (Note 2a, Note 3b, Note 5)		Ear	0.10	mJ	
Channel tempera	nannel temperature		150 °C		
Storage tempera	ture range	T _{stg}	-55~150	°C	



Weight: 0.08 g (typ.)

Circuit Configuration



Note: (Note 1), (Note 2a), (Note 2b), (Note 3a), (Note 3b), (Note 4) and (Note 5): See the next page.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

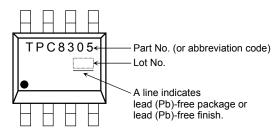
This transistor is an electrostatic-sensitive device. Please handle with caution.

Unit: mm

Thermal Characteristics

Characteristics	Symbol	Max	Unit		
The second second state and the second second	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	83.3		
Thermal resistance, channel to ambient (t = 10s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	125	°C/W	
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	167	0/11	
(t = 10s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a)} (2)	278		

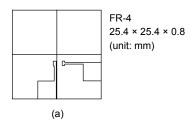
Marking (Note 6)





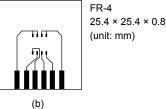
Note 2:

a) Device mounted on a glass-epoxy board (a)





b)



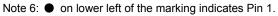
Device mounted on a glass-epoxy board (b)

Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.)

Note 4: V_{DD} = -16 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = -5 A

Note 5: Repetitive rating: pulse width limited by maximum channel temperature



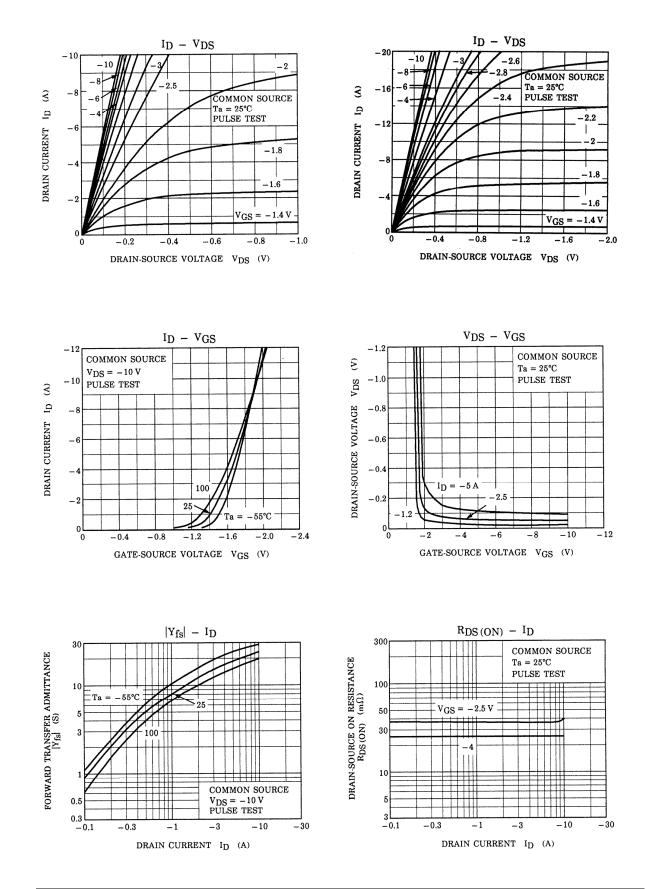


Electrical Characteristics (Ta = 25°C)

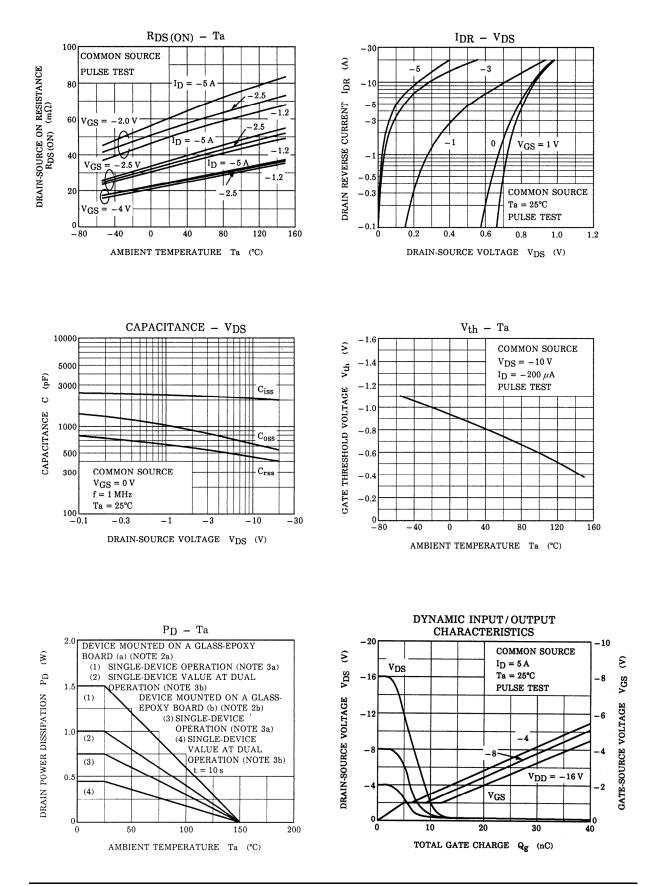
Charao	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	urrent	I _{GSS}	V _{GS} = ±10 V, V _{DS} = 0 V	_	_	±10	μA
Drain cut-off cu	rrent	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μA
Drain-course b	Drain-source breakdown voltage		I _D = -10 mA, V _{GS} = 0 V	-20	_	_	v
Dialit Source bi	eakuown voltage	V (BR) DSS	$I_{\rm D}$ = -10 mA, $V_{\rm GS}$ = 12 V	-8	-	—	•
Gate threshold	voltage	V _{th}	V _{DS} = -10 V, I _D = -200 μA	-0.5	_	-1.2	V
		R _{DS (ON)}	V_{GS} = -2.0 V, I _D = -2.5 A	_	56	80	mΩ
Drain-source ON resistance		R _{DS (ON)}	V_{GS} = -2.5 V, I _D = -2.5 A	_	38	50	mΩ
		R _{DS (ON)}	V_{GS} = -4.5 V, I _D = -2.5 A	_	24	30	mΩ
Forward transfer admittance		Y _{fs}	V _{DS} = -10 V, I _D = -2.5 A	6	12	_	S
Input capacitance		Ciss		_	2030	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	400	_	pF
Output capacitance		Coss		_	580	_	
Switching time	Rise time	tr	$V_{GS} \xrightarrow{0 V} I_D = -2.5 A$	_	25	_	
	Turn-ON time	t _{on}	$V_{GS} \xrightarrow[-5]{0}{} V_{OUT}$ $U_{GS} \xrightarrow[-5]{0}{} V_{OUT}$ $U_{D} \xrightarrow[-5]{0}{} V_{OUT}$ $U_{DD} \xrightarrow[-10]{0}{} V_{DD}$	_	35	_	ns
	Fall time	tf		_	95	_	
	Turn-OFF time	t _{off}	$Duty \le 1\%, t_{W} = 10 \ \mu s$	—	200	—	
Total gate charge (gate-source plus gate-drain)		Qg	V _{DD} ≈ −16 V, V _{GS} = −5 V, I _D = −5 A	_	24	_	
Gate-source charge		Q _{gs}		—	17	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	7	_	

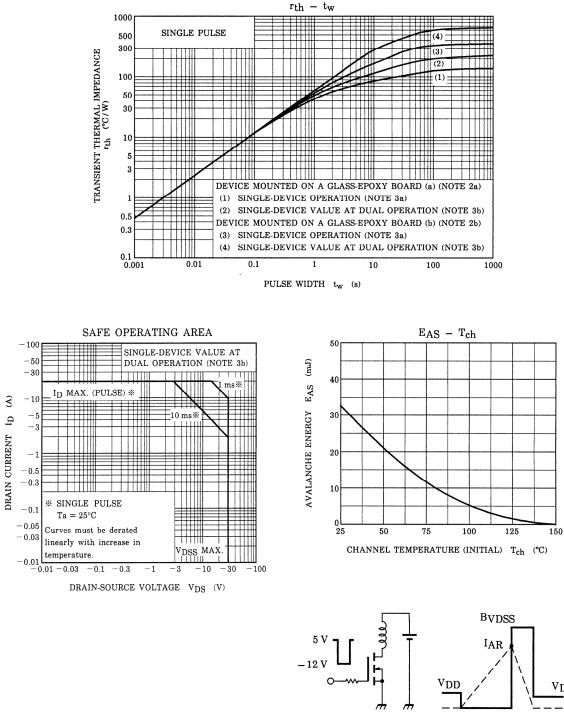
Source–Drain Ratings and Characteristics (Ta = 25°C)

Charact	eristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	—	_	_	-20	A
Forward voltage	(diode)	V _{DSF}	I _{DR} = -5 A, V _{GS} = 0 V	_	_	1.2	V



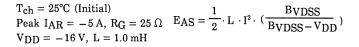
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TEST CIRCUIT

VDS WAVE FORM



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